

## **General Description**

The FDN8601 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

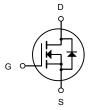
This device is specially designed to get better ruggedness and suitable to use in

# D G SOT-23-3L

#### **General Features**

 $V_{DS}$  =100V  $I_{D}$  =5 A

 $R_{DS(ON)}$  < 140m $\Omega$ @  $V_{GS}$ =10V



#### N-Channel MOSFET

## **Applications**

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

## **Package Marking and Ordering Information**

| Product ID | Pack      | Brand      | Qty(PCS) |
|------------|-----------|------------|----------|
| FDN8601    | SOT-23-3L | HXY MOSFET | 3000     |

Absolute Maximum Ratings (T<sub>C</sub>=25<sup>°</sup>Cunless otherwise noted)

| Symbol                               | Parameter  | Rating | Units |
|--------------------------------------|--|--------|-------|
| VDS                                  | Drain-Source Voltage 100                                       |        |       |
| Vgs                                  | Gate-Source Voltage ±20  |        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C | Continuous Drain Current, V <sub>GS</sub> @ 10V                | 5      | А     |
| I <sub>D</sub> @T <sub>C</sub> =70°C | Continuous Drain Current, V <sub>GS</sub> @ 10V 2.2            |        | А     |
| Ірм                                  | Pulsed Drain Current <sup>2</sup> 11                           |        | А     |
| P <sub>D</sub> @T <sub>C</sub> =25°C | Total Power Dissipation <sup>4</sup>                           | 1      | W     |
| Тѕтс                                 | Storage Temperature Range -55 to 150                           |        | °C    |
| TJ                                   | Operating Junction Temperature Range -55 to 150                |        | °C    |
| R <sub>θ</sub> JC                    | Thermal Resistance from Junction-to-Ambient <sup>3</sup> 80 °C |        | °C/W  |
| Reja                                 | Thermal Resistance Junction-Ambient <sup>1</sup> 125           |        | °C/W  |



# Electrical Characteristics Tc=25°C unless otherwise specified

| Symbol               | Parameter  | Test Condition   | Min. | Тур. | Max. | Units |  |
|----------------------|--|--|------|------|------|-------|--|
| Off Charac           | Off Characteristic   |  |      |      |      |       |  |
| V <sub>(BR)DSS</sub> | Drain-Source Breakdown Voltage                                 | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA               | 100  | 110  | -    | V     |  |
| I <sub>DSS</sub>     | Zero Gate Voltage Drain Current                                | V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V               | -    | -    | 1    | μA    |  |
| Igss                 | Gate to Body Leakage Current                                   | V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V               | -    | -    | ±100 | nA    |  |
| On Charac            | cteristics note3   |  |      |      |      |       |  |
| V <sub>GS(th)</sub>  | Gate Threshold Voltage   | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$                       | 1.0  | 1.95 | 3.0  | V     |  |
| R <sub>DS(on)</sub>  | Static Drain-Source On-Resistance note2                        | V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A                 | -    | 95   | 140  | mΩ    |  |
| Dynamic (            | Characteristics note4  |  | Į.   |      | I.   | l     |  |
| C <sub>iss</sub>     | Input Capacitance  | V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V,<br>f = 1.0MHz | -    | 196  | -    | pF    |  |
| Coss                 | Output Capacitance   |  | -    | 25.9 | -    | pF    |  |
| C <sub>rss</sub>     | Reverse Transfer Capacitance                                   |  | -    | 21.4 | -    | pF    |  |
| Qg                   | Total Gate Charge  | V <sub>DS</sub> = 50V, I <sub>D</sub> = 3A,                | -    | 4.3  | -    | nC    |  |
| Qgs                  | Gate-Source Charge   |  | -    | 3.5  | -    | nC    |  |
| Q <sub>gd</sub>      | Gate-Drain("Miller") Charge                                    | V <sub>GS</sub> = 10V                                      | -    | 3.1  | -    | nC    |  |
| Switching            | Characteristics note4  |  |      |      |      |       |  |
| t <sub>d(on)</sub>   | Turn-On Delay Time   | V <sub>DD</sub> = 50V, I <sub>DS</sub> =3A                 | -    | 14.7 | -    | ns    |  |
| tr                   | Turn-On Rise Time  |  | -    | 3.5  | -    | ns    |  |
| t <sub>d(off)</sub>  | Turn-Off Delay Time  | $R_G = 2\Omega$ , $V_{GEN} = 10V$                          | -    | 20.9 | -    | ns    |  |
| t <sub>f</sub>       | Turn-Off Fall Time   |  | -    | 2.7  | -    | ns    |  |
| Drain-Sou            | rce Diode Characteristics and Maximum Rati                     | ngs  | •    |      |      |       |  |
| Is                   | Maximum Continuous Drain to Source Diode Forward Current note2 |  | -    | -    | 4.5  | Α     |  |
| Ism                  | Maximum Pulsed Drain to Source Diode Forward Current           |  | -    | -    | 12   | Α     |  |
| V <sub>SD</sub>      | Drain to Source Diode Forward Voltage note3                    | V <sub>GS</sub> = 0V, I <sub>S</sub> =3A                   | -    | -    | 1.3  | V     |  |
| t <sub>rr</sub>      | Body Diode Reverse Recovery Time                               | \/ O\/   OA  | -    | 32.1 | -    | ns    |  |
| Qrr                  | Body Diode Reverse Recovery Time Charge                        | $V_{GS} = 0V, I_F = 3A,$                                   | -    | 39.4 | -    | nC    |  |
| Irrm                 | Peak Reverse Recovery Current                                  | di/dt =100A/µs   | -    | 2.1  | -    | Α     |  |

### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤2%.
- 4. Guaranteed by design, not subject to production
- 5.  $V_{DD}$ =50 V,  $R_G$ =50  $\Omega$ , L=0.3 mH, starting  $T_j$ =25 °C



## **Typical Characteristics**

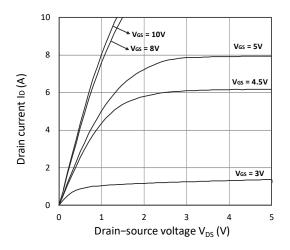


Figure 1. Output Characteristics

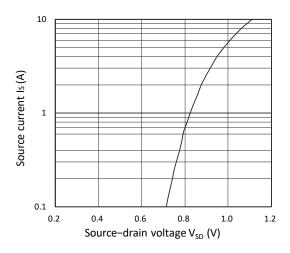


Figure 3. Forward Characteristics of Reverse

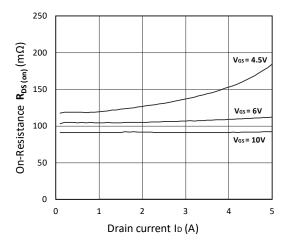


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ 

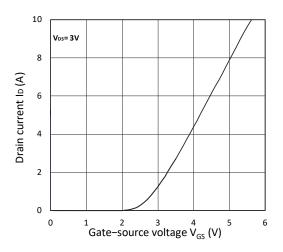


Figure 2. Transfer Characteristics

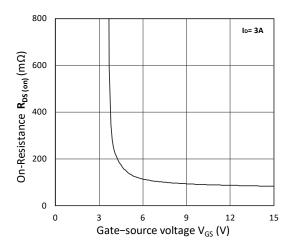


Figure 4.  $R_{\text{DS(ON)}}\,$  vs.  $V_{\text{GS}}\,$ 

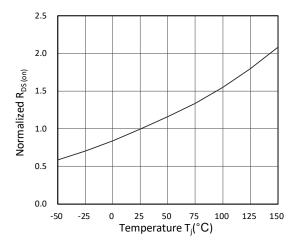


Figure 6. Normalized  $R_{\text{DS(on)}}$  vs. Temperature

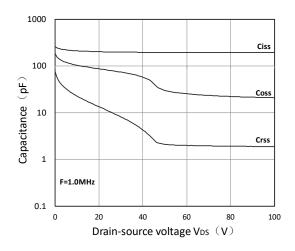


Figure 7. Capacitance Characteristics

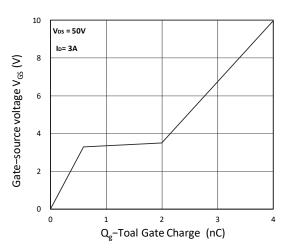
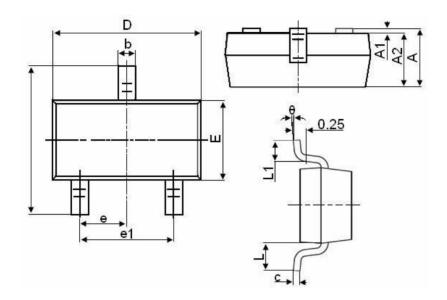


Figure 8. Gate Charge Characteristics

# **SOT-23-3L Package Information**



| Symbol | Dimensions in Millimeters |          |  |
|--------|---------------------------|----------|--|
|        | MIN.                      | MAX.     |  |
| А      | 1.050                     | 1.250    |  |
| A1     | 0.000                     | 0.100    |  |
| A2     | 1.050                     | 1.150    |  |
| b      | 0.300                     | 0.500    |  |
| С      | 0.100                     | 0.200    |  |
| D      | 2.800                     | 3.000    |  |
| Е      | 1.500                     | 1.700    |  |
| E1     | 2.650                     | 2.950    |  |
| е      |                           | 0.950TYP |  |
| e1     | 1.800                     | 2.000    |  |
| L      | 0.550REF                  |          |  |
| L1     | 0.300                     | 0.600    |  |
| θ      | 0°                        | 8°       |  |



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